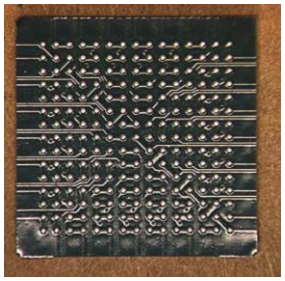
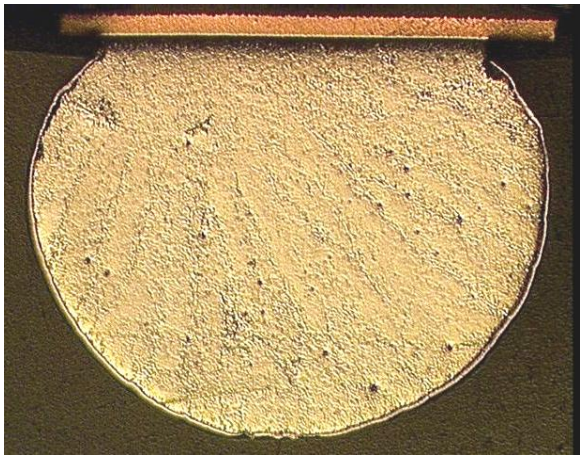
Package Characteristics: BGA Sn63

Top View

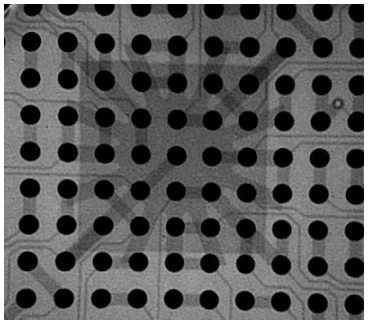


Bottom View

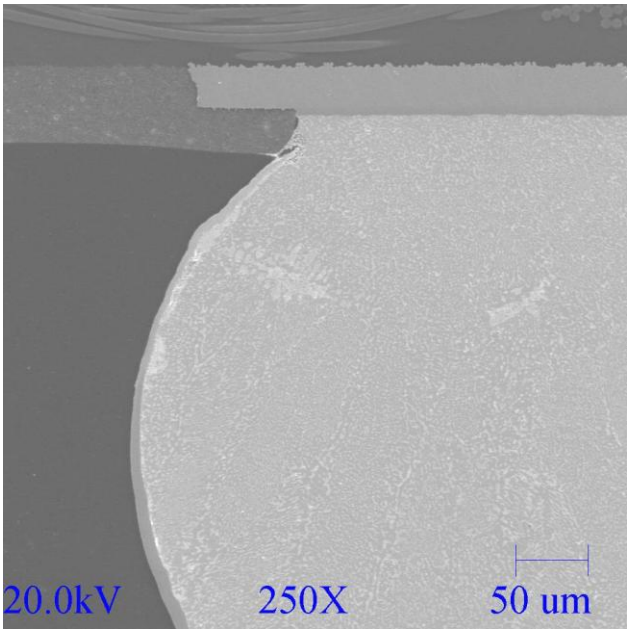
Feature	Value
Package Length	27.00 mm
Package Width	26.99 mm
Package Thickness	1.70 mm
Diameter of Solder Balls	0.80 mm
Die Length	8.38 mm
Die Width	8.38 mm
Die Thickness	0.29 mm
Pitch	1.50 mm
Weight	2.3351 g
CTE	15.30 ppm/C
Width of Solder ball in contact with component pad	0.591 mm
Solderball Alloy (SEM estimate)	Sn63Pb37



Cross-section of solder ball



X-ray



SEM of solder ball cross-section